



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-08-22
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	CNG6*F174AA9	A	Z7GA	2018-08-22
Amount	UoM	Unit type	ST ECOPACK Grade	
36	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5x5x1	32	flat	
Comment	A06C VFQFPN 5X5X1.0 32L WET FLK; MDF valid for BLUENRG-232			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	CNG6*F174AA9				5999998.0	1000002.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	3.494	mg	supplier	die	Silicon (Si)	7440-21-3		3.258	mg	932456	90500
				supplier	metallization	Aluminium (Al)	7429-90-5		0.011	mg	3148	306
				supplier	metallization	Copper (Cu)	7440-50-8		0.100	mg	28620	2778
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.032	mg	9159	889
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	286	28
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	286	28
				supplier	Passivation	Silicon Nitride	12033-89-5		0.026	mg	7441	722
				supplier	Passivation	Silicon Oxide	7631-86-9		0.065	mg	18603	1806
Leadframe	M-004 Copper and its alloys	10.551	mg	supplier	Alloy	Copper (Cu)	7440-50-8		10.112	mg	958393	280889
				supplier	Alloy	Chromium	7440-47-3		0.028	mg	2654	778
				supplier	Alloy	Tin (Sn)	7440-31-5		0.025	mg	2369	694
				supplier	Alloy	Zinc (Zn)	7440-66-6		0.020	mg	1896	556
				supplier	metallization	Silver (Ag)	7440-22-4		0.366	mg	34689	10167
Die Attach	M-015 Other organic materials	2.433	mg	supplier	Glue	Silver (Ag)	7440-22-4		1.983	mg	815043	55083
				supplier	Glue	(Octahydro-4,7-methano-1 H-indenediy)bis(m	42594-17-2		0.146	mg	60008	4056
				supplier	Glue	exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl met	7534-94-3		0.146	mg	60008	4056
				supplier	Glue	Isobornyl acrylate	5888-33-5		0.146	mg	60008	4056
				supplier	Glue	2-(3,4-Epoxy cyclohexyl)ethyltrimethoxysilane	3388-04-3		0.012	mg	4932	333
Bonding wire	M-011 Other inorganic materials	0.479	mg	supplier	wire	Gold (Au)	7440-57-5		0.475	mg	991649	13194
				supplier	wire	Platinum (Pt)	7440-06-4		0.003	mg	6263	83
				supplier	wire	Palladium (Pd)	7440-05-3		0.001	mg	2088	28
Encapsulation	M-015 Other organic materials	16.898	mg	supplier	Molding compound	Epoxy Resin	25068-38-6		0.845	mg	50006	23472
				supplier	Molding compound	Phenol Resin	29690-82-2		0.389	mg	23020	10806
				supplier	Molding compound	Silica (Amorphous)A	60676-86-0		14.362	mg	849923	398944
				supplier	Molding compound	Silica (Amorphous)B	7631-86-9		0.845	mg	50006	23472
				supplier	Molding compound	Metal Hydroxide	proprietary		0.389	mg	23020	10806
supplier	Molding compound	Carbon Black	1333-86-4		0.068	mg	4024	1889				
Finishing	M-011 Other inorganic materials	2.145	mg	supplier	connection coating	Tin (Sn)	7440-31-5		2.145	mg	1000000	59583